

1.6X0.8mm SMD CHIP LED LAMP (0.25mm Height)



Part Number: APG1608ZGC

Green

Features

- 1.6mmX0.8mm SMT LED, 0.25mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

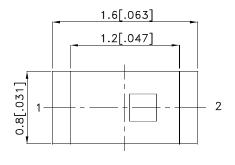
Descriptions

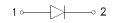
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

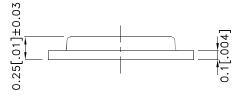
Applications

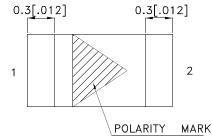
1. Mobile phone Keypad indicator and backlight. 2.Flat backlight for LCD, switch and symbol. 3.Toys.

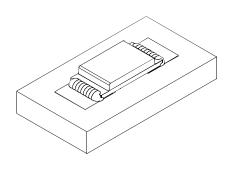
Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APG1608ZGC	Green (InGaN)	Water Clear	200	400	120°

Notes:

- 1. 01 / 2 is the angle from optical centerline where the luminous intensity is 1 / 2 of the optical peak value.
 2. Luminous intensity / luminous Flux: + / -15%.
 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	515		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	525		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.3	4.1	V	IF=20mA
lr	Reverse Current	Green		50	uA	V _R =5V

- 1. Wavelength: + / -1nm.

- 1. vvaverengur. + / IIIII.
 2. Forward Voltage: + / 0.1V.
 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

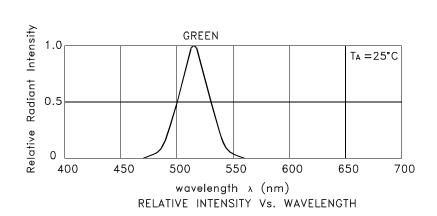
Absolute Maximum Ratings at TA=25°C

Parameter	Green		
Power dissipation	102.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Electrostatic Discharge Threshold (HBM)	450	V	
perating Temperature -40°C To +85°C			
Storage Temperature	-40°C To +85°C		

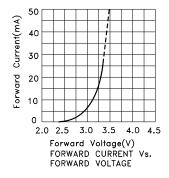
Note: 1. 1 / 10 Duty Cycle, 0.1ms Pulse Width.

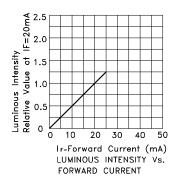
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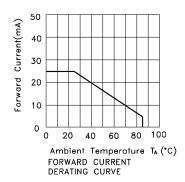
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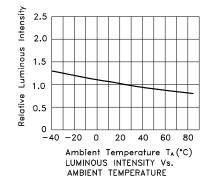


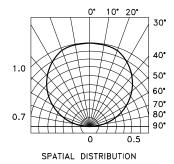
Green APG1608ZGC











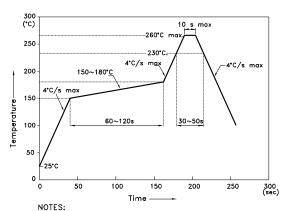
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



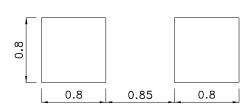
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

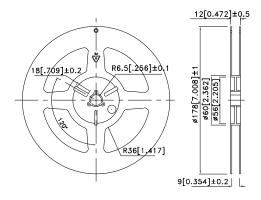
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



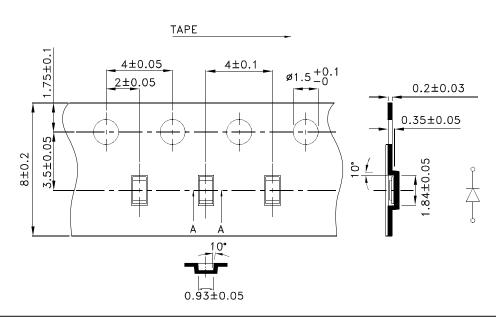
Reel Dimension



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Tape Dimensions (Units: mm)

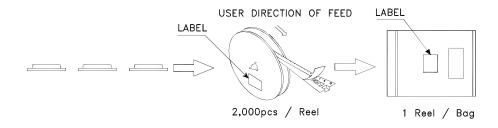


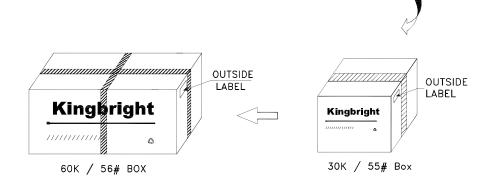
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PACKING & LABEL SPECIFICATIONS

APG1608ZGC







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